

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

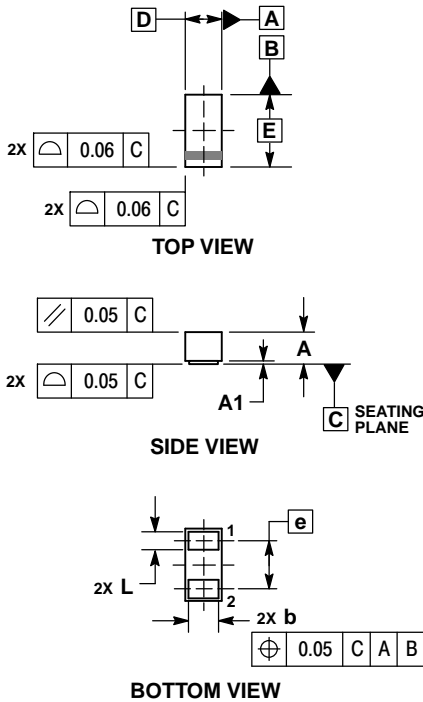
ON Semiconductor®



DSN2, 0.6x0.3, 0.4P, (0201)
CASE 152AA
ISSUE B


SCALE 8:1

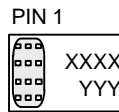
DATE 30 APR 2017



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS.

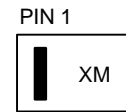
MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.30
A1	0.00	0.01
b	0.20	0.22
D	0.30	BSC
E	0.60	BSC
e	0.40	BSC
L	0.10	0.12

GENERIC MARKING DIAGRAM1*



XXXX = Specific Device Code
YYY = Year Code

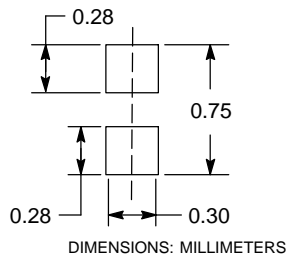
GENERIC MARKING DIAGRAM2*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

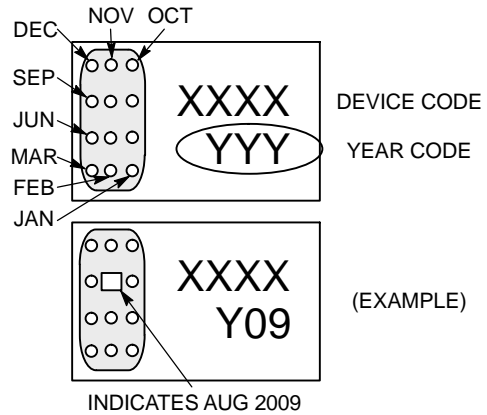
MOUNTING FOOTPRINT*



See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

CATHODE BAND MONTH CODING



DOCUMENT NUMBER:	98AON39897E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DSN2, 0.6X0.3, 0.4P, (0201)	PAGE 1 OF 2

